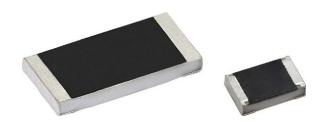


www.vishay.com

Vishay Draloric

High Voltage (Up to 2 kV) Thick Film Chip Resistors



The RCV e3 high voltage thick film chip resistors series are the perfect choice for modern electronics with high voltage requirements. Typical applications include E-meter, AC power supplies, lighting ballasts and inverters for industrial drives, aircons, and white good.

FEATURES

- High operating voltage (up to 2 kV)
- Low voltage coefficient of resistance (VCR): 25 ppm/V



 Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- E-meter
- · Inverters for industrial drives, aircons, and white good
- AC power supplies
- · Lighting ballasts

TECHNICAL SPECIFICATIONS						
DESCRIPTION	RCV0805 e3	RCV1206 e3	RCV2010 e3			
Imperial size	0805	1206	2010			
Metric size code	RR2012M	RR3216M	RR5025M			
Resistance range		100 k Ω to 10 M Ω				
Resistance tolerance		± 5 %; ± 1 %				
Temperature coefficient	± 200 ppm/K; ± 100 ppm/K					
Voltage coefficient Icl of resistance chart		25 ppm/V				
Rated dissipation, P ₇₀ ⁽¹⁾	0.125 W	0.25 W	0.75 W			
Operating voltage, U _{max.} AC _{RMS} /DC	400 V	500 V	2000 V			
Permissible film temperature, $\vartheta_{\text{F max.}}^{(1)}$		155 °C				
Operating temperature range		-55 °C to +155 °C				
Max. resistance change at P_{70} for resistance range, $ \Delta R/R $ after:						
1000 h	≤ 1.0 %	≤ 1.0 %	≤ 2.0 %			

Notes

- · Application-specific safety requirements may set limitations to the applicability of the specified voltage
- (1) Please refer to APPLICATION INFORMATION below

APPLICATION INFORMATION

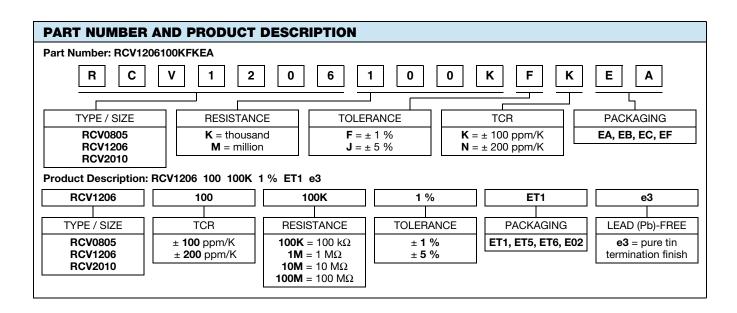
When the resistor dissipates power, a temperature rise above the ambient temperature occurs, dependent on the thermal resistance of the assembled resistor together with the printed circuit board. The rated dissipation applies only if the permitted film temperature is not exceeded.

These resistors do not feature a limited lifetime when operated within the permissible limits. However, resistance value drift increasing over operating time may result in exceeding a limit acceptable to the specific application, thereby establishing a functional lifetime.



TEMPERATURI	TEMPERATURE COEFFICIENT AND RESISTANCE RANGE							
TYPE / SIZE	TCR	TOLERANCE	RESISTANCE	E-SERIES				
RCV0805 e3	± 200 ppm/K	± 5 %	100 kΩ to 10 MΩ	E24				
NO \$0003 e3	± 100 ppm/K	± 1 %	CE RESISTANCE	E24; E96				
RCV1206 e3	± 200 ppm/K	± 5 %	100 kΩ to 10 MΩ	E24				
NOV 1200 63	± 100 ppm/K	TCR TOLERANCE ± 200 ppm/K ± 5 % ± 100 ppm/K ± 1 % ± 200 ppm/K ± 5 %	100 kΩ to 10 MΩ	E24; E96				
RCV2010 e3	### TCR ################################	± 5 %	100 kΩ to 10 MΩ	E24				
11042010 63	± 100 ppm/K	± 1 %	100 k Ω to 10 M Ω	E24; E96				

PACKAGING								
TYPE / SIZE	CODE	QUANTITY	PACKAGING STYLE	WIDTH	PITCH	PACKAGING DIMENSIONS		
	EA = ET1	5000				Ø 180 mm / 7"		
RCV0805 e3	EB = ET5 10 000		Ø 285 mm / 11.25"					
	EC = ET6	20 000	Paper tape according to IEC 60286-3, type 1a 8 mm 4 mm	0 mm	4	Ø 330 mm / 13"		
	EA = ET1	5000		4 111111	Ø 180 mm / 7"			
RCV1206 e3	EB = ET5	10 000				Ø 285 mm / 11.25"		
	EC = ET6	20 000				Ø 330 mm / 13"		
RCV2010 e3	EF = E02	4000	Blister tape according to IEC 60286-3, type 2a	12 mm	4 mm	Ø 180 mm / 7"		





DESCRIPTION

Production is strictly controlled and follows an extensive set of instructions established for reproducibility. A cermet film layer and a glass-over are deposited on a high grade (Al_2O_3) ceramic substrate. Specially designed inner contacts are deposited on both sides. A special laser is used to achieve the target value by smoothly fine trimming the resistive layer without damaging the ceramics. The resistor elements are covered by a protective coating designed for electrical, mechanical, and climatic protection. The terminations receive a final pure tin on nickel plating. The result of the determined production is verified by an extensive testing procedure on 100 % of the individual chip resistors. Only accepted products are laid directly into the tape in accordance with IEC 60286-3 type 1a and 2a (1).

ASSEMBLY

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using wave, reflow or vapor phase as shown in **IEC 61760-1** ⁽¹⁾. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters, and aqueous solutions. The suitability of conformal coatings, potting compounds and their processes, if applied, shall be qualified by appropriate means to ensure the long-term stability of the whole system.

The resistors are RoHS-compliant, the pure tin plating provides compatibility with lead (Pb)-free and lead-containing soldering processes. Solderability is specified for 2 years after production or requalification. The permitted storage time is 20 years. The immunity of the plating against tin whisker growth has been proven under extensive testing.

MATERIALS

Vishay acknowledges the following systems for the regulation of hazardous substances:

- IEC 62474, Material Declaration for Products of and for the Electrotechnical Industry, with the list of declarable substances given therein (2)
- The Global Automotive Declarable Substance List (GADSL) (3)
- The REACH regulation (1907/2006/EC) and the related list of substances with very high concern (SVHC) (4) for its supply chain

The products do not contain any of the banned substances as per IEC 62474, GADSL, or the SVHC list, see www.vishay.com/how/leadfree.

Hence the products fully comply with the following directives:

- 2000/53/EC End-of-Life Vehicle Directive (ELV) and Annex II (ELV II)
- 2011/65/EU Restriction of the Use of Hazardous Substances Directive (RoHS) with amendment 2015/863/EU
- 2012/19/EU Waste Electrical and Electronic Equipment Directive (WEEE)

Vishay pursues the elimination of conflict minerals from its supply chain, see the Conflict Minerals Policy at www.vishay.com/doc?49037.

APPROVALS

Where applicable, the resistors are tested in accordance with **EN 140401-802** which refers to **EN 60115-1**, **EN 60115-8** and the variety of environmental test procedures of the **IEC 60068** ⁽¹⁾ series.

RELATED PRODUCTS

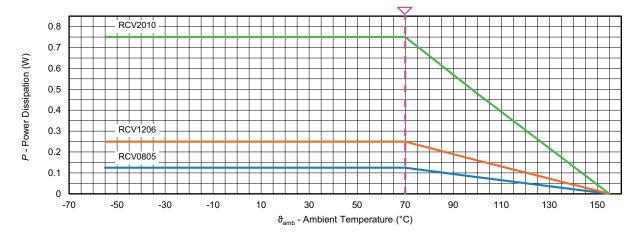
For high voltage thin film products, please refer to latest edition of TNPV e3, High Voltage Thin Film Chip Resistors datasheet, www.vishav.com/doc?28881.

For products with professional specification, please refer to latest edition of MMA0204 HV, MMB0207 HV, Professional High Voltage Thin Film MELF Resistors datasheet, www.vishay.com/doc?28880.

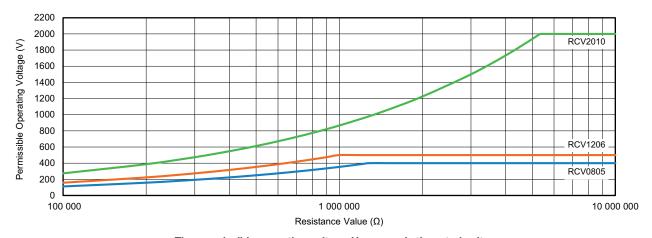
Notes

- (1) The quoted IEC standards are also released as EN standards with the same number and identical contents
- (2) The IEC 62474 list of declarable substances is maintained in a dedicated database, which is available at http://std.iec.ch/iec62474
- (3) The Global Automotive Declarable Substance List (GADSL) is maintained by the American Chemistry Council and available at www.gadsl.org
- (4) The SVHC list is maintained by the European Chemical Agency (ECHA) and available at http://echa.europa.eu/candidate-list-table

DERATING



NOMINAL OPERATING VOLTAGE



The permissible operating voltage $U_{\rm max.}$ equals the rated voltage. For ambient temperatures above 70 °C power derating must be considered

TESTS AND REQUIREMENTS

All executed tests are carried out in accordance with the following specifications:

EN 60115-1, generic specification

EN 60115-8 (successor of ΕN 140400), sectional specification

EN 140401-802, detail specification

IEC 60068-2-xx, test methods

The parameters stated in the "Test Procedures and Requirements" table are based on the required tests and permitted limits of EN 140401-802. The table presents only the most important tests, for the full test schedule refer to the documents listed above. However, some additional tests and a number of improvements against those minimum requirements have been included.

The testing also covers most of the requirements specified by EIA/IS-703 and JIS-C-5201-1.

The tests are carried out under standard atmospheric conditions in accordance with IEC 60068-1, 4.3, whereupon the following values are applied:

Temperature: 15 °C to 35 °C Relative humidity: 25 % to 75 %

Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar)

A climatic category LCT / UCT / 56 is applied, defined by the lower category temperature (LCT), the upper category temperature (UCT), and the duration of exposure in the

damp heat, steady state test (56 days).

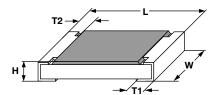


IEC			PROCEDURE			REQUIREMENTS PERMISSIBLE CHANGE (\(\triangle R \))		
EN 60115-1 CLAUSE	1 115-1 60082-2 ⁽¹⁾ TEST TEST					STABILITY CLASS 1 OR BETTER	STABILITY CLASS 2 OR BETTER	
CLAUSE	METHOD		Stability fo	r product ty	/pes:	100 kΩ to 10 MΩ		
					RCV e3	7.55 1.52 1.5 1.71		
4.5	-	Resistance		-		± 1 %	± 5 %	
4.8	-	Temperature coefficient	At (20 / -55 / 20) °C and (20 / 155 / 20) °C			± 100 ppm/K	± 200 ppm/K	
4.25.1	-	Endurance at 70 °C	whiche	P ₇₀ x R or U ever is the le .5 h on; 0.5 70 °C; 100	ess severe; h off	RCV0805, RCV1206: ± (1 % R + 0.05 RCV2010: ± (2 % R + 0.1 Ω)		
4.25.3	-	Endurance at upper category temperature		155 °C; 10	00 h	± (2 % F	' + 0.1 Ω)	
4.24	78 (Cab)	Damp heat, steady state) ± 2) °C; 56 (93 ± 3) %		± (1 % R + 0.05 Ω)	± (2 % R + 0.1 Ω)	
4.23	-	Climatic sequence:						
4.23.2	2 (Bb)	Dry heat	125 °C; 16 h					
4.23.3	30 (Db)	Damp heat, cyclic	55 °C; 24 h; ≥ 90 % RH; 1 cycle					
4.23.4	1 (Ab)	Cold	-55 °C: 2 h		± (1 % R + 0.05 Ω)	\pm (2 % R + 0.1 Ω)		
4.23.5	13 (M)	Low air pressure	8.5 kPa; 2 h; (25 ± 10) °C					
4.23.6	30 (Db)	Damp heat, cyclic	55 °C; 5 days; > 90 % RH; 5 cycles					
4.23.7	-	DC load	$U = (P_{70} \times R)^{1/2} \le U_{\text{max.}}; 1 \text{ min}$					
-	1 (Aa)	Cold		-55 °C; 2	h	± (0.5 % R + 0.05 Ω)		
4.19	14 (Na)	Rapid change of temperature	30 min. at -55 °C and 30 min. at 125 °C; RCV 0805 RCV1206: 1000 cycles RCV2010: 100 cycles		\pm (1 % R + 0.05 Ω) no visible damage			
					$2^2 \le 2 \times U_{\text{max.}};$ s severe; 5 s			
4.10		Short time avarland		Duration	Maximum U _{OL}	RCV0805, RCV1206:	± (0.25 % R + 0.05 Ω)	
4.13	-	- Short time overload	RCV0805	1 s	800	RCV2010: \pm (2.0 % R + 0.05 Ω)		
			RCV1206	2 s	1000			
			RCV2010	5 s	3000			
4.27	-	Single pulse high voltage overload 10 µs / 700 µs	$U = 10 \times (P)$	Severity no $P_{70} \times R)^{1/2}$ os the less se	o. 4: r <i>U</i> = 2 x <i>U</i> _{max.;} evere; 10 pulses		$r + 0.1 \Omega$) e damage	
4.39	-	Periodic electric overload	whiche	ver is the le	J = 2 x U _{max.} ; ess severe; 1000 cycles	± (2 % <i>R</i> + 0.05 Ω) no visible damage		
4.38	-	Electrostatic discharge (human body model)	IEC 61340-3-1 ⁽¹⁾ ; 3 positive + 3 negative discharges; RCV0805: 1000 V RCV1206: 2000 V RCV2010: 12 000 V		± (1 % R	+ 0.05 Ω)		
4.22	6 (Fc)	Vibration	Endurance by sweeping f = 10 Hz to 2000 Hz; no resonance; A ≤ 1.5 mm ≤ 200 m/s²; 7.5 h			± (0.25 % R + 0.05 Ω) no visible damage	± (0.5 % R + 0.05 Ω) no visible damage	
4.17	58 (Td)	Solderability	Solder bath method, SnPb40; non-activated flux (235 ± 5) °C; (2 ± 0.2) s Solder bath method, Sn96.5Ag3Cu0.5;			95 % covered); e damage		
			(245	on-activate ± 5) °C; (3	± 0.3) s			
4.18	58 (Td)	Resistance to soldering heat		lering bath $0 \pm 5)$ °C; (1		$\pm (0.25 \% R + 0.05 \Omega)$	± (0.5 % R + 0.05 Ω)	

TEST P	TEST PROCEDURES AND REQUIREMENTS							
	IEC		PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (△R)				
EN 60115-1 CLAUSE	60082-2 ⁽¹⁾ TEST	TEST	PROCEDURE	STABILITY CLASS 1 OR BETTER	STABILITY CLASS 2 OR BETTER			
CLAUSE	METHOD		Stability for product types:	100 100	OM 01 01			
			RCV e3	100 kΩ to 10 MΩ				
4.29	45 (XA)	Component solvent resistance	Isopropyl alcohol; +50 °C; method 2	No visible damage				
4.32	21 (Uu ₃)	Shear (adhesion)	17.7 N	No visible damage				
4.33	21 (Uu ₁)	Substrate bending	Depth 2 mm; 3 times	RCV0805, RCV1206: ± (0.25 % R + 0.05 RCV2010: ± (1 % R + 0.05 Ω) no visible damage, no open circuit in bent position				
4.7	-	Voltage proof	$U = 1.4 \times U_{ins}$; 60 s	No flashover or breakdown				
4.35	-	Flammability, needle flame test	IEC 60695-11-5 ⁽¹⁾ ; 10 s	No burning after 30 s				

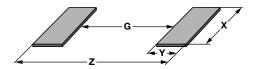
Note

DIMENSIONS



DIMENSIONS AND MASS								
TYPE / SIZE	L (mm)	W (mm)	H (mm)	T1 (mm)	T2 (mm)	MASS (mg)		
RCV0805 e3	2.0 + 0.20 / - 0.10	1.25 ± 0.15	0.45 ± 0.05	0.3 + 0.20 / - 0.10	0.3 ± 0.20	5.5		
RCV1206 e3	3.2 + 0.20 / - 0.10	1.6 ± 0.15	0.55 ± 0.05	0.45 ± 0.20	0.4 ± 0.20	10		
RCV2010 e3	5.0 ± 0.15	2.5 ± 0.15	0.6 ± 0.10	0.6 ± 0.20	0.45 ± 0.20	25.5		

SOLDER PAD DIMENSIONS



RECOMMENDED SOLDER PAD DIMENSIONS									
		WAVE SO	LDERING		REFLOW SOLDERING				
TYPE / SIZE	G (mm)	Y (mm)	X (mm)	Z (mm)	G (mm)	Y (mm)	X (mm)	Z (mm)	
RCV0805 e3	0.90	1.30	1.60	3.50	1.00	0.95	1.45	2.90	
RCV1206 e3	1.40	1.40	1.95	4.20	1.50	1.05	1.80	3.60	
RCV2010 e3	3.60	1.65	2.85	6.90	3.70	1.20	2.70	6.10	

Note

⁽¹⁾ The quoted IEC standards are also released as EN standards with the same number and identical contents

Utilization of the full specified operating voltage may require special considerations on the creepage and clearance distance between conductors at different potential levels



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